

T-43-21

# CD4011A, CD4012A, CD4023A Types

## CMOS NAND Gates

Quad 2 Input — CD4011A  
 Dual 4 Input — CD4012A  
 Triple 3 Input — CD4023A

The RCA-CD4011A, CD4012A, and CD4023A NAND gates provide the system designer with direct implementation of the NAND function and supplement the existing family of CMOS gates.

These types are supplied in 14-lead hermetic dual-in-line ceramic packages (D and F suffixes), 14-lead dual-in-line plastic packages (E suffix), 14-lead ceramic flat packages (K suffix), and in chip form (H suffix).

### Features:

- Quiescent current specified to 15 V
- Maximum input leakage of 1  $\mu$ A at 15 V (full package-temperature range)
- 1-V noise margin (full package-temperature range)

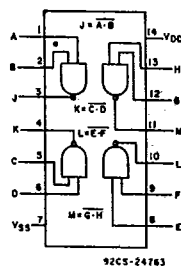
### RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

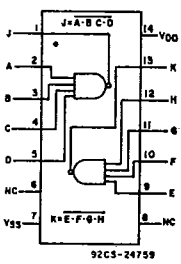
Characteristic	Min.	Max.	Units
Supply Voltage Range (over full package temperature range)	3	12	V

### MAXIMUM RATINGS, Absolute-Maximum Values:

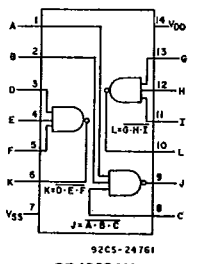
- STORAGE-TEMPERATURE RANGE ( $T_{stg}$ ) ..... -65 to +150°C  
 OPERATING-TEMPERATURE RANGE ( $T_A$ ):  
 PACKAGE TYPES D, F, K, H ..... -55 to +125°C  
 PACKAGE TYPE E ..... -40 to +85°C  
 DC SUPPLY-VOLTAGE RANGE, ( $V_{DD}$ )  
 (Voltages referenced to  $V_{SS}$  Terminal): ..... -0.5 to +15 V  
 POWER DISSIPATION PER PACKAGE ( $P_D$ ):  
 FOR  $T_A = -40$  to +60°C (PACKAGE TYPE E) ..... 500 mW  
 FOR  $T_A = +60$  to +85°C (PACKAGE TYPE E) ..... Derate Linearly at 12 mW/°C to 200 mW  
 FOR  $T_A = -55$  to +100°C (PACKAGE TYPES D, F, K) ..... 500 mW  
 FOR  $T_A = +100$  to +125°C (PACKAGE TYPES D, F, K) ..... Derate Linearly at 12 mW/°C to 200 mW  
 DEVICE DISSIPATION PER OUTPUT TRANSISTOR  
 FOR  $T_A =$  FULL PACKAGE-TEMPERATURE RANGE (ALL PACKAGE TYPES) ..... 100 mW  
 INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5 to  $V_{DD} + 0.5$  V  
 LEAD TEMPERATURE (DURING SOLDERING):  
 At distance 1/16  $\pm$  1/32 inch (1.59  $\pm$  0.79 mm) from case for 10 s max ..... +265°C



CD4011A

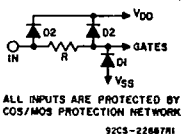


CD4012A



CD4023AH

Fig. 1 — Functional diagrams.



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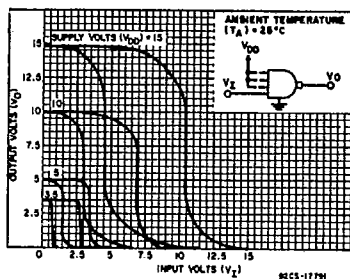


Fig. 2 — Minimum & maximum voltage transfer characteristics.

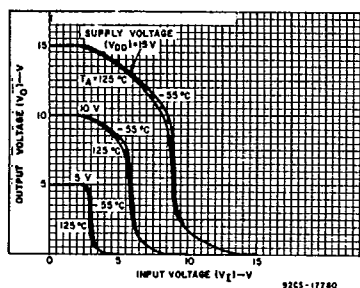


Fig. 3 — Typical voltage transfer characteristics as a function of temperature.

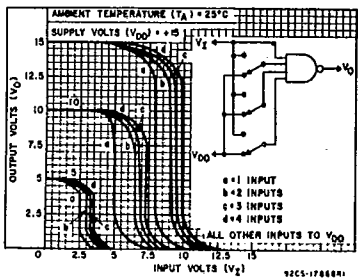


Fig. 4 — Typical multiple input switching transfer characteristics for CD4012A.

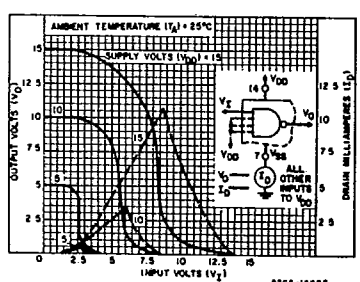


Fig. 5 — Typical current & voltage transfer characteristics.

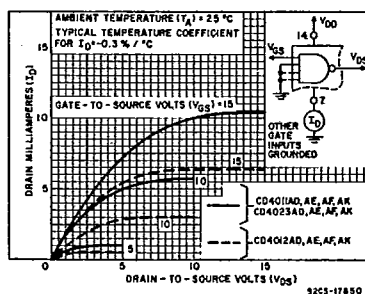


Fig. 6 — Typical n-channel drain characteristics.

CD4011A, CD4012A, CD4023A Types

STATIC ELECTRICAL CHARACTERISTICS

Characteristic	Conditions			Limits at Indicated Temperatures (°C)								Units
				D, F, K, H Packages				E Package				
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	+25		+125	-40	+25		+85	
Quiescent Device Current, I <sub>Q</sub> Max.	-	-	5	0.05	0.001	0.05	3	0.5	0.005	0.5	15	μA
	-	-	10	0.1	0.001	0.1	6	5	0.005	5	30	
	-	-	15	2	0.02	2	40	50	0.5	50	500	
Output Voltage: Low-Level VOL	-	0.5	5	0 Typ.; 0.05 Max.								V
	-	0.10	10	0 Typ.; 0.05 Max.								
	-	0.5	5	4.95 Min.; 5 Typ.								
High Level, VOH	-	0.10	10	9.95 Min.; 10 Typ.								V
	-	0.10	10	9.95 Min.; 10 Typ.								
Noise Immunity: Inputs Low, V <sub>NL</sub>	3.6	-	5	1.5 Min.; 2.25 Typ.								V
	7.2	-	10	3 Min.; 4.5 Typ.								
Inputs High, V <sub>NH</sub>	1.4	-	5	1.5 Min.; 2.25 Typ.;								V
	2.8	-	10	3 Min.; 4.5 Typ.								
Noise Margin: Inputs Low, V <sub>NML</sub>	4.5	-	5	1 Min.								V
	9	-	10	1 Min.								
Inputs High, V <sub>NMH</sub>	0.5	-	5	1 Min.								V
	1	-	10	1 Min.								
Output Drive Current: N-Channel (Sink) I <sub>DN</sub> Min.	CD4011A	0.5	5	0.31	0.5	0.25	0.175	0.145	0.5	0.12	0.095	mA
			10	0.62	0.6	0.5	0.35	0.3	0.8	0.25	0.2	
	CD4012A	5	0.15	0.25	0.12	0.085	0.072	0.25	0.06	0.05		
		10	0.31	0.6	0.25	0.175	0.155	0.6	0.13	0.105		
	P-Channel (Source), I <sub>DP</sub> Min.	All Types	5	-0.31	-0.5	-0.25	-0.175	-0.145	-0.5	-0.12	-0.095	
			10	-0.75	-1.2	-0.6	-0.4	-0.35	-1.2	-0.3	-0.24	
Input Leakage Current, I <sub>IL</sub> , I <sub>IH</sub>	Any Input	15	±10 <sup>-5</sup> Typ.; ±1 Max.								μA	

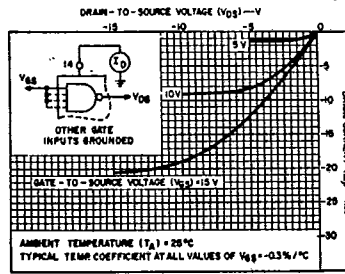


Fig. 7 - Typical p-channel drain characteristics.

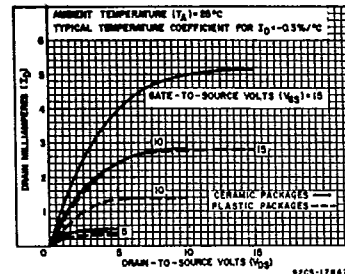


Fig. 8 - Minimum n-channel drain characteristics - CD4011A & CD4023A.

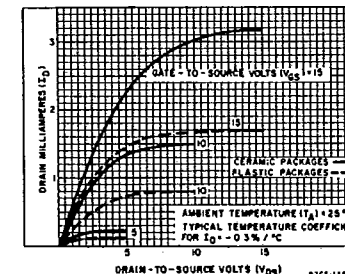


Fig. 9 - Minimum n-channel drain characteristics.

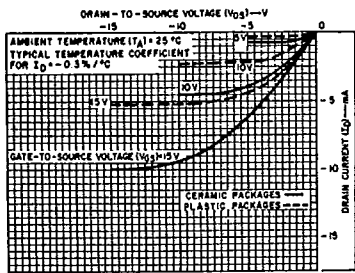


Fig. 10 - Minimum p-channel drain characteristics.

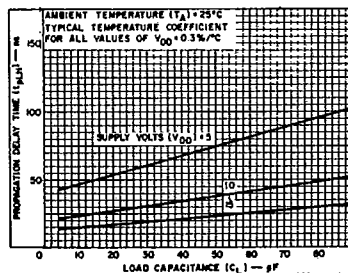


Fig. 11 - Typical low-to-high level propagation delay time vs. CL.

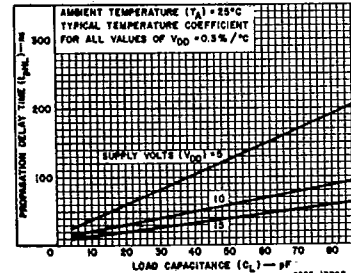


Fig. 12 - Typical high-to-low level propagation delay time vs. CL - CD4011A, & CD4023A.

# CD4011A, CD4012A, CD4023A Types

DYNAMIC ELECTRICAL CHARACTERISTICS at  $T_A = 25^\circ\text{C}$ ,  $C_L = 15\text{ pF}$ , Input  $t_r, t_f = 20\text{ ns}$ ,  $R_L = 200\text{ K}\Omega$

CHARACTERISTICS	TEST CONDITIONS	LIMITS				UNITS	
		D, F, K, H Packages		E Package			
		VDD (V)	Typ.	Max.	Typ.		Max.
Propagation Delay Time: Low-to-High Level, $t_{PLH}$		5	50	75	50	100	ns
		10	25	40	25	50	
High-to-Low Level, $t_{PHL}$ CD4011A and CD4023A		5	50	75	50	100	ns
		10	25	40	25	50	
CD4012A		5	100	150	100	200	ns
		10	50	75	50	100	
Transition Time: Low-to-High Level, $t_{TLH}$		5	75	100	75	125	ns
		10	40	60	40	75	
High-to-Low Level, $t_{THL}$ CD4011A and CD4023A		5	75	125	75	150	ns
		10	50	75	50	100	
CD4012A		5	250	375	250	500	ns
		10	125	200	125	250	
Input Capacitance, $C_i$	Any Input	5	-	5	-	-	pF

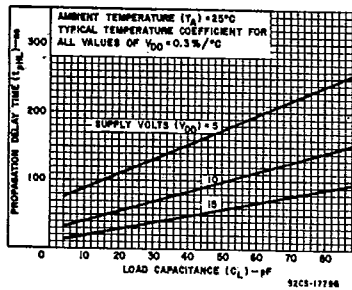


Fig. 13 - Typical high-to-low level propagation delay time vs.  $C_L$  - CD4012A.

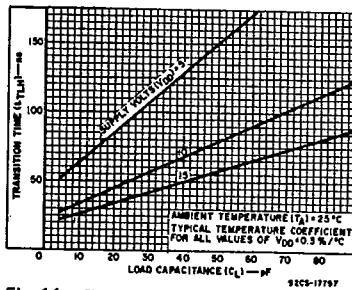


Fig. 14 - Typical low-to-high transition time vs.  $C_L$ .

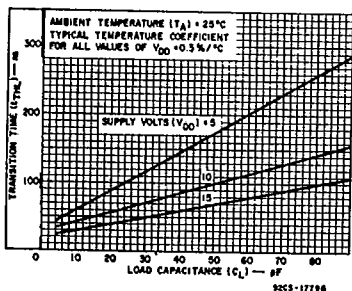


Fig. 15 - Typical high-to-low level transition time vs.  $C_L$  - CD4011A & CD4023A.

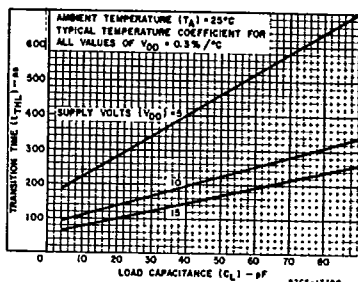


Fig. 16 - Typical high-to-low level transition time vs.  $C_L$  - CD4012A.

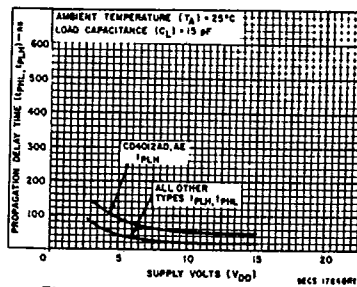


Fig. 17 - Minimum propagation delay time vs.  $V_{DD}$ .

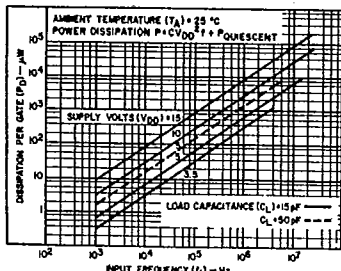


Fig. 18 - Typical dissipation characteristics.

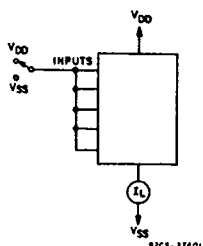


Fig. 19 - Quiescent device current test circuit.

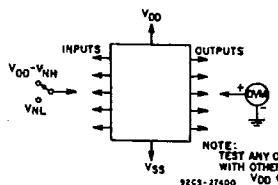


Fig. 20 - Noise immunity test circuit.

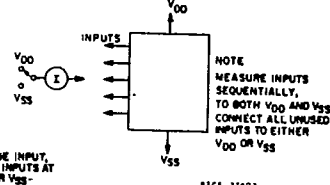
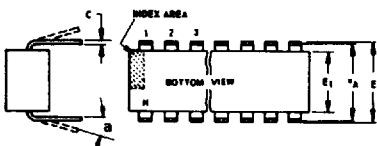
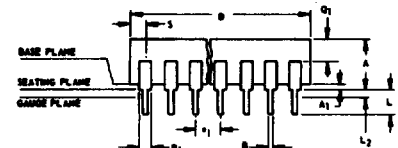


Fig. 21 - Input leakage current test circuit.

## Dimensional Outlines

### Dual-In-Line Welded-Seal Ceramic Packages



**NOTES:**

- Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
- Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
- e<sub>A</sub> applies in zone L<sub>2</sub> when unit installed.
- a applies to spread leads prior to installation.
- N is the maximum quantity of lead positions.
- N<sub>1</sub> is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-001-AD)  
14-Lead Dual-In-Line Welded-Seal  
Ceramic Package

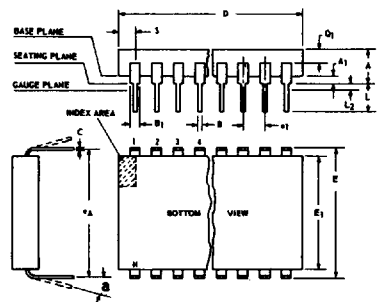
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A <sub>1</sub>	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B <sub>1</sub>	0.060	0.065		1.27	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.770		18.93	19.55
E	0.300	0.325		7.62	8.25
E <sub>1</sub>	0.240	0.260		6.10	6.60
e <sub>1</sub>	0.100 TP		2	2.54 TP	
e <sub>A</sub>	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L <sub>2</sub>	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	14		5	14	
N <sub>1</sub>	0		6	0	
Q <sub>1</sub>	0.060	0.085		1.27	2.15
S	0.065	0.090		1.66	2.28

92SS-4411R2

(D) SUFFIX (JEDEC MO-001-AE)  
16-Lead Dual-In-Line Welded-Seal  
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.120	0.160		3.05	4.06
A <sub>1</sub>	0.020	0.065		0.51	1.65
B	0.014	0.020		0.356	0.508
B <sub>1</sub>	0.035	0.065		0.89	1.65
C	0.008	0.012	1	0.204	0.304
D	0.745	0.785		18.93	19.93
E	0.300	0.325		7.62	8.25
E <sub>1</sub>	0.240	0.260		6.10	6.60
e <sub>1</sub>	0.100 TP		2	2.54 TP	
e <sub>A</sub>	0.300 TP		2, 3	7.62 TP	
L	0.125	0.150		3.18	3.81
L <sub>2</sub>	0.000	0.030		0.000	0.76
a	0°	15°	4	0°	15°
N	16		5	16	
N <sub>1</sub>	0		6	0	
Q <sub>1</sub>	0.050	0.085		1.27	2.15
S	0.015	0.060		0.39	1.52

92SS-4266R5



- NOTES:**  
Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).
  - Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
  - e<sub>A</sub> applies in zone L<sub>2</sub> when unit installed.
  - a applies to spread leads prior to installation.
  - N is the maximum quantity of lead positions.
  - N<sub>1</sub> is the quantity of allowable missing leads.

(D) SUFFIX (JEDEC MO-015-AG)  
24-Lead Dual-In-Line Welded-Seal  
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5.08
A <sub>1</sub>	0.020	0.070		0.51	1.78
B	0.015	0.020		0.381	0.508
B <sub>1</sub>	0.045	0.055		1.143	1.397
C	0.008	0.012	1	0.204	0.304
D	1.15	1.22		29.21	30.98
E	0.600	0.625		15.24	15.87
E <sub>1</sub>	0.480	0.520		12.20	13.20
e <sub>1</sub>	0.100 TP		2	2.54 TP	
e <sub>A</sub>	0.600 TP		2, 3	15.24 TP	
L	0.100	0.180		2.54	4.57
L <sub>2</sub>	0.000	0.030		0.00	0.76
a	0°	15°	4	0°	15°
N	24		5	24	
N <sub>1</sub>	0		6	0	
Q <sub>1</sub>	0.020	0.080		0.51	2.03
S	0.020	0.060		0.51	1.52

92CS-19948R4

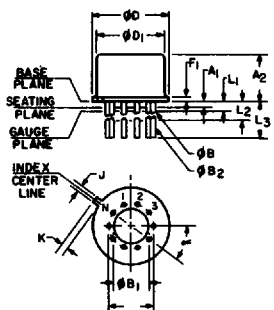
(D) SUFFIX (JEDEC MO-015-AH)  
28-Lead Dual-In-Line Welded-Seal  
Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.090	0.200		2.29	5
A <sub>1</sub>	0	0.070	2	0	1.77
B	0.015	0.020		0.381	0.508
B <sub>1</sub>	0.015	0.065		0.39	1.39
C	0.008	0.012	1	0.204	0.304
D	1.380	1.420		35.06	36.06
E	0.600	0.625		15.24	15.87
E <sub>1</sub>	0.485	0.515		12.32	13.08
e <sub>1</sub>	0.100 TP		2	2.54 TP	
e <sub>A</sub>	0.600 TP		2, 3	15.24 TP	
L	0.100	0.200		2.6	5
L <sub>2</sub>	0	0.030		0	0.76
a	0°	15°	4	0°	15°
N	28		5	28	
N <sub>1</sub>	0		6	0	
Q <sub>1</sub>	0.020	0.070		0.51	1.77
S	0.040	0.070		1.02	1.77

92CM-20250R2

### TO-5 Style Package

(T) SUFFIX (JEDEC MO-006-AG)  
12-Lead Metal Package



92CS-19774

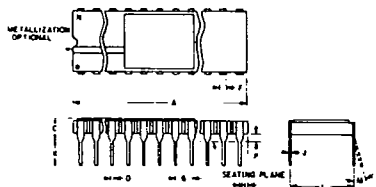
SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
a	0.230		2	5.84 TP	
A <sub>1</sub>	0	0		0	0
A <sub>2</sub>	0.165	0.185		4.19	4.70
φB	0.018	0.019	3	0.407	0.482
φB <sub>1</sub>	0	0		0	0
φB <sub>2</sub>	0.016	0.021	3	0.407	0.533
φD	0.335	0.370		8.51	9.39
φD <sub>1</sub>	0.305	0.335		7.75	8.50
F <sub>1</sub>	0.020	0.040		0.51	1.01
j	0.028	0.034		0.712	0.863
k	0.029	0.045	4	0.74	1.14
L <sub>1</sub>	0.000	0.050	3	0.00	1.27
L <sub>2</sub>	0.250	0.500	3	6.4	12.7
L <sub>3</sub>	0.500	0.562	3	12.7	14.27
a	30° TP			30° TP	
N	12		6	12	
N <sub>1</sub>	1		5	1	

**NOTES:**

- Refer to Rules for Dimensioning Axial Lead Product Outlines.
- Leads at gauge plane within 0.007" (0.178 mm) radius of True Position (TP) at maximum material condition.
- φB applies between L<sub>1</sub> and L<sub>2</sub>. φB<sub>2</sub> applies between L<sub>2</sub> and 0.500" (12.70 mm) from seating plane. Diameter is uncontrolled in L<sub>1</sub> and beyond 0.500" (12.70 mm).
- Measure from Max. φD.
- N<sub>1</sub> is the quantity of allowable missing leads.
- N is the maximum quantity of lead positions.

Dimensional Outlines (Cont'd)

DUAL-IN-LINE SIDE-BRAZED CERAMIC PACKAGES



(D) SUFFIX  
18-Lead Dual-in-Line  
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.890	0.915		22.606	23.241
C	-	0.200		-	5.080
D	0.015	0.021		0.381	0.533
F	0.054	REF.	1	1.371	REF.
G	0.100	BSC	1	2.54	BSC
H	0.035	0.065		0.889	1.651
J	0.008	0.012	3	0.203	0.304
K	0.125	0.150		3.175	3.810
L	0.290	0.310	2	7.366	7.874
M	0°	15°		0°	15°
P	0.025	0.045		0.635	1.143
N	18			18	

92CS-27231R1

(D) SUFFIX  
22-Lead Dual-in-Line  
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.065	1.100		27.05	27.94
C	0.085	0.145		2.16	3.68
D	0.017	0.023		0.43	0.58
F	0.040	REF.	1	1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.380	0.420	2	9.65	10.67
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	22			22	

92CS-25186R2

NOTES:

- Leads within 0.005" (0.13 mm) radius of True Position at maximum material condition.
- Dimension "L" to center of leads when formed parallel.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013" (0.33 mm).

(D) SUFFIX  
24-Lead Dual-in-Line  
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.180	1.220		29.98	30.98
C	0.085	0.145		2.16	3.68
D	0.015	0.023		0.39	0.58
F	0.040	REF.		1.02	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.77	1.77
J	0.008	0.012	3	0.21	0.30
K	0.125	0.175		3.18	4.44
L	0.580	0.620	2	14.74	15.74
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	24			24	

92CS-30968R1

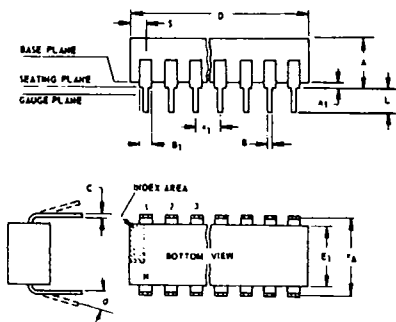
(D) SUFFIX  
40-Lead Dual-in-Line  
Side-Brazed Ceramic Package

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	1.980	2.020		50.30	51.30
C	0.095	0.155		2.43	3.93
D	0.017	0.023		0.43	0.58
F	0.050	REF.		1.27	REF.
G	0.100	BSC	1	2.54	BSC
H	0.030	0.070		0.76	1.78
J	0.008	0.012	3	0.20	0.30
K	0.125	0.175		3.18	4.45
L	0.580	0.620	2	14.74	15.74
M	-	7°		-	7°
P	0.025	0.050		0.64	1.27
N	40			40	

92CM-27029R2

Dual-In-Line Plastic and Frit-Seal Ceramic Packages

(E) SUFFIX (JEDEC MO-001-AN)  
8-Lead Dual-In-Line Plastic  
(Mini-DIP) Package



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.155	0.200		3.94	5.08
A <sub>1</sub>	0.020	0.050		0.508	1.27
B	0.014	0.020		0.356	0.508
B <sub>1</sub>	0.035	0.065		0.889	1.65
C	0.008	0.012	1	0.203	0.304
D	0.370	0.400		9.40	10.16
E	0.300	0.325		7.62	8.25
E <sub>1</sub>	0.240	0.260		6.10	6.60
e <sub>1</sub>	0.100	TP	2	2.54	TP
e <sub>A</sub>	0.300	TP	2, 3	7.62	TP
L	0.125	0.150		3.18	3.81
L <sub>2</sub>	0.000	0.030		0.000	0.762
a	0	15	4	0	15
N	8		5	8	
N <sub>1</sub>	0		6	0	
O <sub>1</sub>	0.040	0.075		1.02	1.90
S	0.015	0.060		0.381	1.52

92CS-24026R1

NOTES:

- Refer to Rules for Dimensioning (JEDEC Publication No. 95) for Axial Lead Product Outlines.
- When this device is supplied solder-dipped, the maximum lead thickness (narrow portion) will not exceed 0.013".
  - Leads within 0.005" (0.12 mm) radius of True Position (TP) at gauge plane with maximum material condition and unit installed.
  - e<sub>A</sub> applies in zone L<sub>2</sub> when unit installed.
  - a applies to spread leads prior to installation.
  - N is the maximum quantity of lead positions.
  - N<sub>1</sub> is the quantity of allowable missing leads.

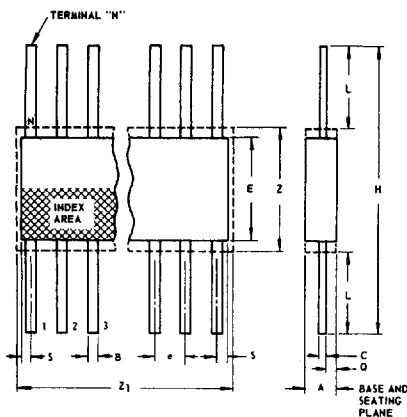


T-90-20

**Dimensional Outlines (Cont'd)**

**Ceramic Flat Packs**

**(K) SUFFIX (JEDEC MO-004-AF)  
14-Lead**



SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	14		3	14	
Q	0.005	0.050		0.13	1.27
S	0.000	0.050		0.00	1.27
Z	0.300		4	7.62	
Z <sub>1</sub>	0.400		4	10.16	

92SS-4300R3

**NOTES:**

1. Refer to JEDEC Publication No. 95 for Rules for Dimensioning Peripheral Lead Outlines.
2. Leads within 0.005" (0.12 mm) radius of True Position (TP) at maximum material condition.
3. N is the maximum quantity of lead positions.
4. Z and Z<sub>1</sub> determine a zone within which all body and lead irregularities lie.

**(K) SUFFIX (JEDEC MO-004-AG)  
16-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.008	0.100		0.21	2.54
B	0.015	0.019	1	0.381	0.482
C	0.003	0.006	1	0.077	0.152
e	0.050 TP		2	1.27 TP	
E	0.200	0.300		5.1	7.6
H	0.600	1.000		15.3	25.4
L	0.150	0.350		3.9	8.8
N	16		3	16	
Q	0.005	0.050		0.13	1.27
S	0.000	0.025		0.00	0.63
Z	0.300		4	7.62	
Z <sub>1</sub>	0.400		4	10.16	

92CS-17271R3

**(K) SUFFIX  
24-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	24		3	24	
Q	0.035	0.070		0.89	1.77
S	0.060	0.110	1	1.53	2.79
Z	0.700		4	17.78	
Z <sub>1</sub>	0.750		4	19.05	

92CS-19949R2

**(K) SUFFIX  
28-Lead**

SYMBOL	INCHES		NOTE	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	0.075	0.120		1.91	3.04
B	0.018	0.022	1	0.458	0.558
C	0.004	0.007	1	0.102	0.177
e	0.050 TP		2	1.27 TP	
E	0.600	0.700		15.24	17.78
H	1.150	1.350		29.21	34.29
L	0.225	0.325		5.72	8.25
N	28		3	28	
Q	0.035	0.070		0.89	1.77
S	0	0.060	1	0	1.53
Z	0.700		4	17.78	
Z <sub>1</sub>	0.750		4	19.05	

92CS-20972